



25th International Conference on Electronic Packaging Technology

August 07 to 09, 2024, Tianjin, China

<http://www.icept.org>

Speech subject: Requirements of Chiplet integration on process, material and equipment of IC packaging.

Speech leader: Tonglong Zhang—Sr Expert, Hisilicon

Speech Description/Objective:

Requirements of chiplet integration on process, material and equipment of IC packaging

Who Should Attend:

Teacher, students, equipment and material suppliers

Introduction of Speaker:

Tonglong Zhang have ~28 years of IC packaging experience. He worked at companies at various position in the semiconductor supplier chain including design house, OSAT and IDM. He has worked on design, stress and thermal, process and material development and reliability assessment. He has developed various IC packaging technologies including fine pitch cu pillar flipchip csp, large size flipchip package, 2.5D package etc. He have 10 US patents and several Chinese patents on IC packaging.